

ABSTRACT

Provided is an adhesive composition for forming an adhesive layer used for temporarily bonding a semiconductor substrate or an electronic device layer to a support substrate, wherein, after the semiconductor substrate or the electronic device layer and the support substrate are temporarily bonded to each other via the adhesive layer, a force required to insert a tool having a sharp portion between the semiconductor substrate or the electronic device layer and the support substrate, when the semiconductor substrate or the electronic device layer is mechanically peeled from the support substrate using the tool, is 10.0 kgf or less, and the adhesive layer has a storage modulus of 30 MPa or greater.

FIG. 1